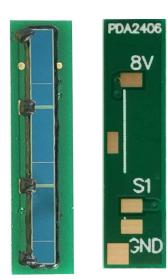
Technical Data Sheet

PIN Photodiode Array: PDA6220

■ Features

- . 3 photodiodes
- . Fast response time
- . High photo sensitivity
- . Pb free
- . The product itself will remain within RoHS compliant version.



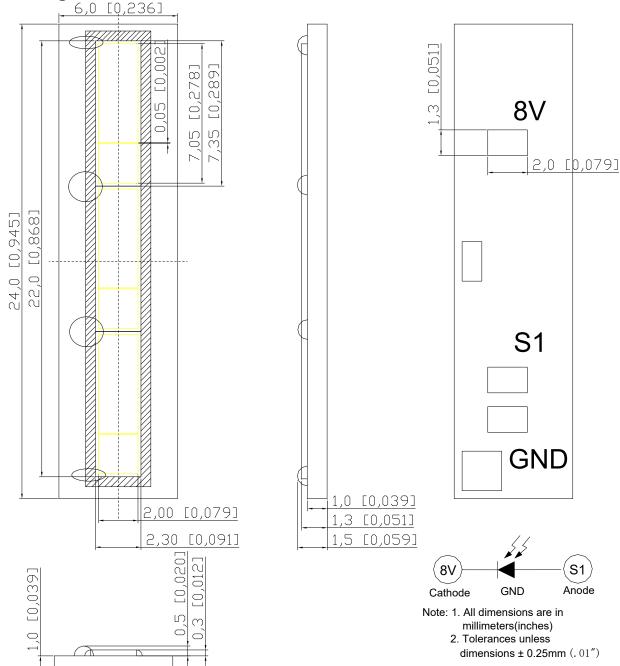
Descriptions

PDA6220 (PDA2406) is a high sensitive and high speed silicon photodiodes mounted on PCB. Spliced into a long strip photo diode.

■ Applications

- . Window sensor
- . Microcurrent power supply

■ Package Dimensions



■ Absolute Maximum Ratings (Ta=25°C)

issolute manifest (14 20 0)								
Parameter	Symbol	Rating	Units					
Reverse Voltage	VR	30	V					
Power Dissipation	Pd	150	mW					
Lead Soldering Temperature	Tsol	260	°C					
Operating Temperature	Topr	-20 ∼ +85	°C					
Storage Temperature	Tstg	-40 ~ +85	°C					

■ Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Units
Range of Spectral Bandwidth	λ 0.5		400		1100	nm
Wavelength of Peak	λp			940		10.00
Sensitivity				940		nm
Open-Circuit Voltage	Voc	Note(1)		0.39		V
Short- Circuit Current	Isc	Note(1)		480		μА
Reverse Light Current	IL	Note(1) V _R =5V		480		μА
Dark Current	Id	Ee=0m W/cm2			30	nA
		$V_R=10V$				
Reverse Breakdown Voltage	BVR	Ee=0m W/cm2	60			V
		I _R =100 μ A				
Total Capacitance	Ct	Ee=0m W/cm2				
		$V_R=5V$		63		рF
		f=1MHZ				
Rise/Fall Time	tr/tf	$V_R=10V$		150/150		C
		$R_L=1K\Omega$				nS

Note(1):Parallel light of Ee=5mW/cm2 illumination is applied by a Tungsten lamp of 2856K

■ Typical Electro-Optical Characteristics Curves

Fig.1 Power Dissipation vs.

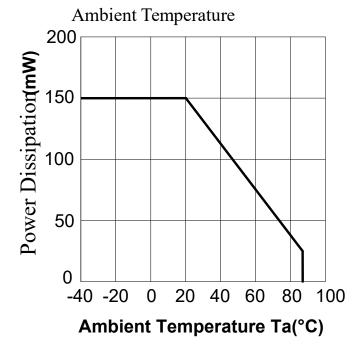


Fig.2 Spectral Sensitivity

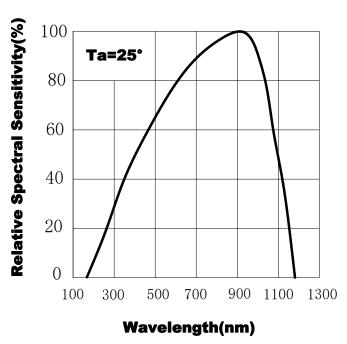


Fig.3 Dark Current vs.



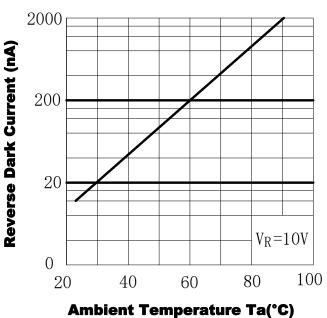
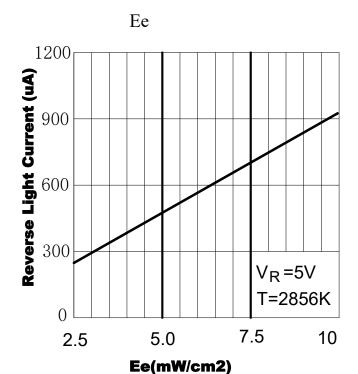
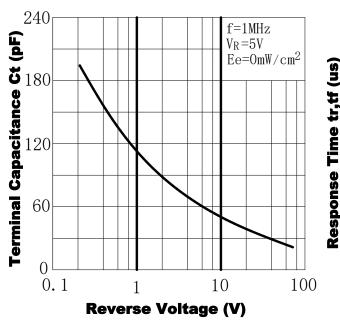


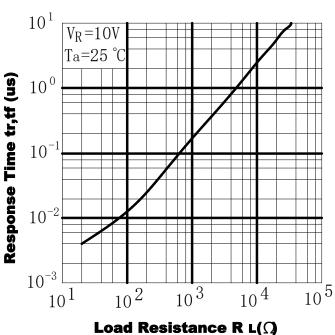
Fig.4 Reverse Light Current vs.



Terminal Capacitance vs. Fig.5 Reverse Voltage

Fig.6 Response Time vs. Load Resistance





■ Notes

- 1. Above specification may be changed without notice. SHUGUAN will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. SHUGUAN assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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 corporation. Please don't reproduce or cause anyone to reproduce them without SHUGUAN's
 consent.
- 4. This products is bare chip products (wafers or diced chips), Unsealed products are not protected by an external enclosure and so require especially strict care to prevent physical breakage or contamination. It has protective tape, which is removed prior to use.
- 5. Condensation may form on the chip surface in environments subject to sharp or sudden fluctuations in temperature, so avoid use in such locations.
- 6. Applying excessive force to the product using a printed circuit board may cause the board to warp. This warping may damage the chip, wires connections, so use caution.
- 7. Do not let anything come in contact with the chip surface. Though the chip is hard, it is also brittle an easily notched. Sharped or hard items that come in contact with the chip may case cracks or scratches, which can lead to fluctuations in electrical characteristics or poor device reliability.
- 8. This kind of products due to the customer's external dimensions, performance parameters and other requirements are different, standard products are difficult to meet customer needs, the company provides customized services, can be developed and designed by our company new products, can also provide customers with processing and generation services.